

HD74AC00

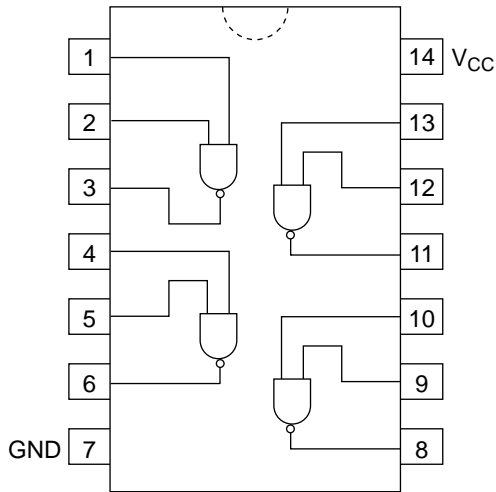
Quad 2-Input NAND Gate

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Feature

- Outputs Source/Sink 24 mA

Pin Arrangement



(Top view)

DC Characteristics (unless otherwise specified)

| Item | Symbol | Max | Unit | Condition |
|----------------------------------|----------|-----|---------------|--|
| Maximum quiescent supply current | I_{CC} | 40 | μA | $V_{IN} = V_{CC}$ or ground, $V_{CC} = 5.5 \text{ V}$, $T_a = \text{Worst case}$ |
| Maximum quiescent supply current | I_{CC} | 4.0 | μA | $V_{IN} = V_{CC}$ or ground, $V_{CC} = 5.5 \text{ V}$, $T_a = 25^\circ\text{C}$ |

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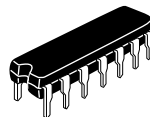
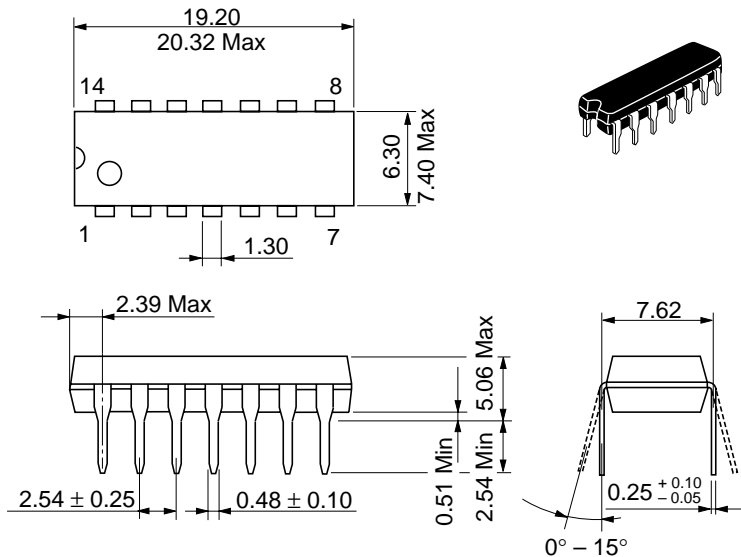
AC Characteristics

| Item | Symbol | V_{CC} (V) ^{*1} | $T_a = +25^{\circ}\text{C}$ $C_L = 50\text{ pF}$ | | | $T_a = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $C_L = 50\text{ pF}$ | | Unit |
|-------------------|-----------|----------------------------|---|-----|-----|---|------|------|
| | | | Min | Typ | Max | Min | Max | |
| Propagation delay | t_{PLH} | 3.3 | 1.0 | 7.0 | 9.5 | 1.0 | 10.0 | ns |
| | | 5.0 | 1.0 | 6.0 | 8.0 | 1.0 | 8.5 | |
| Propagation delay | t_{PHL} | 3.3 | 1.0 | 5.5 | 8.0 | 1.0 | 8.5 | ns |
| | | 5.0 | 1.0 | 4.5 | 6.5 | 1.0 | 7.5 | |

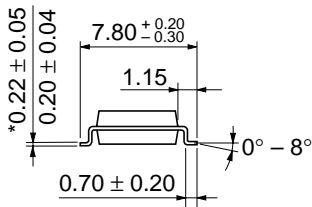
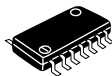
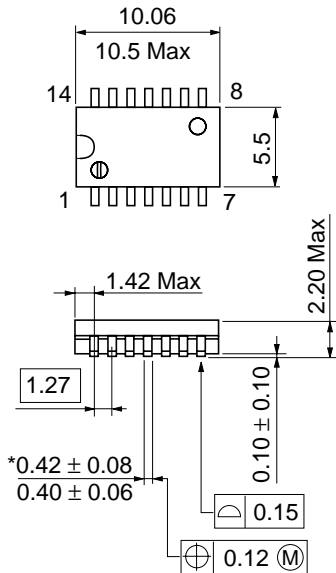
Note: 1. Voltage Range 3.3 is $3.3\text{ V} \pm 0.3\text{ V}$
Voltage Range 5.0 is $5.0\text{ V} \pm 0.5\text{ V}$

Capacitance

| Item | Symbol | Typ | Unit | Condition |
|-------------------------------|----------|------|------|-------------------------|
| Input capacitance | C_{IN} | 4.5 | pF | $V_{CC} = 5.5\text{ V}$ |
| Power dissipation capacitance | C_{PD} | 30.0 | pF | $V_{CC} = 5.0\text{ V}$ |

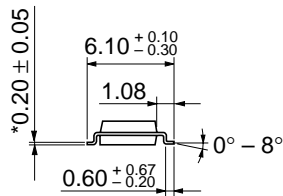
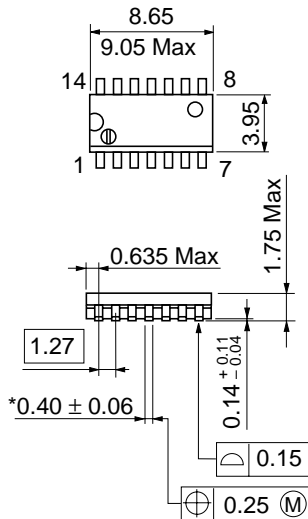


| | |
|--------------------------|----------|
| Hitachi Code | DP-14 |
| JEDEC | Conforms |
| EIAJ | Conforms |
| Weight (reference value) | 0.97 g |

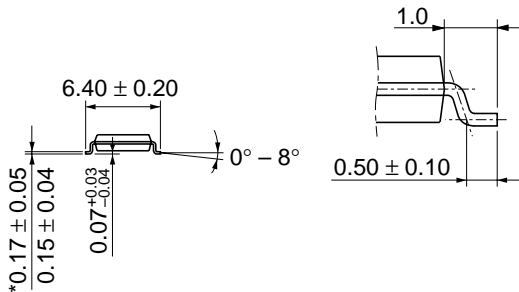
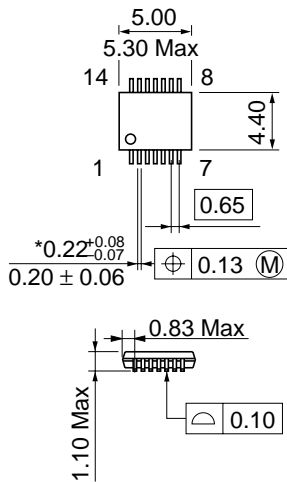


| | |
|--------------------------|----------|
| Hitachi Code | FP-14DA |
| JEDEC | — |
| EIAJ | Conforms |
| Weight (reference value) | 0.23 g |

*Dimension including the plating thickness
Base material dimension



| | |
|--------------------------|----------|
| Hitachi Code | FP-14DN |
| JEDEC | Conforms |
| EIAJ | Conforms |
| Weight (reference value) | 0.13 g |



*Dimension including the plating thickness
 Base material dimension

| | |
|--------------------------|---------|
| Hitachi Code | TTP-14D |
| JEDEC | — |
| EIAJ | — |
| Weight (reference value) | 0.05 g |

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Hitachi, Ltd.

Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL North America : <http://semiconductor.hitachi.com/>
 Europe : <http://www.hitachi-eu.com/hel/ecg>
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For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1> (408) 433-0223

Hitachi Europe GmbH
Electronic components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building, No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX

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